

Please amend the claims as indicated below:

1. (Currently amended) A method of processing an unsingulated array of packaged semiconductor devices electronic component comprising the steps of:
providing mounting means;
mounting the unsingulated electronic components onto the array on a mounting means device; then singulating the components packaged semiconductor devices to physically separate them the packages; and then
testing the singulated electronic components packaged semiconductor devices for defects while they are mounted on the mounting means device and without removal therefrom.
2. (Currently amended) A method according to claim 1, further comprising the step of applying markings to distinguish non-defective ones of the electronic components packaged semiconductor devices from defective ones after testing while they are still mounted on the mounting means device.
3. (Previously presented) A method according to claim 2, wherein the singulation, testing and marking steps are carried out at two or more stations.
4. (Currently amended) A method according to claim 3, including the step of moving the electronic components packaged semiconductor devices at least between the testing and marking positions for testing and marking respectively.
5. (Currently amended) A method according to claim 1, which includes further including the step of detecting the alignments of electronic components the packaged semiconductor devices before testing, and orienting the array of electronic components packaged devices as desired before implementing testing.

6. (Currently amended) A method according to claim 2, wherein the markings are applied with a laser device which generates by directing a laser beam, for effecting marking onto selected ones of the packages

7. (Currently amended) A method according to claim 6, wherein:
the mounting means device comprises a film of laser transparent tape with an adhesive on one surface;
wherein each electronic component is the packaged semiconductor devices are mounted on the adhesive surface of the film of transparent tape; and
marking is effected by passing the laser beam generated by the laser device through the film of laser transparent tape toward the adhesive surface thereof,
the surface of the electronic component packaged semiconductor device being marked being the one in contact with the adhesive surface of the tape.

8. (Currently amended) An apparatus for processing an unsingulated array of electronic components packaged semiconductor devices comprising:
a mounting means device for mounting [[an]] the unsingulated array of electronic components packaged semiconductor devices;
a singulating device for singulating the said array of electronic components packaged semiconductor devices; and
a testing device operative to test each of the said singulated electronic components packaged semiconductor devices for defects;
whereby singulation and testing of the singulated electronic components packaged semiconductor devices are conducted while they are mounted on the mounting means device without removal therefrom.

9. (Currently amended) An apparatus according to claim 8, including an inscribing device for applying markings to distinguish defective and non-defective tested electronic components packaged semiconductor devices while they are mounted on the mounting means device.

10. (Previously presented) An apparatus according to claim 9, wherein the singulation, testing and marking are carried out at two or more stations of the apparatus.

11. (Currently amended) An apparatus according to claim 10, including moving means a conveyor for moving the electronic components packaged semiconductor devices for processing at least between the testing and marking positions.

12. (Currently amended) An apparatus according to claim 11, wherein the moving means convcyor is adapted to move the electronic components in packaged semiconductor devices relative to linear and rotary axes, such as an XYZ Theta table.

13. (Currently amended) An apparatus according to claim 8, wherein the mounting means device comprises a film of material having an adhesive on one side and stretched on a support frame, and having an adhesive on one side for receiving the packaged semiconductor devices and whereby electronic components are mountable on the adhesive side.

14. (Currently amended) An apparatus according to claim 13, wherein there is further including a vacuum chuck for holding in operative to maintain the position of the support frame and film on which electronic components are mountable, during the singulation, testing and marking of the packaged semiconductor deviccs.

15. (Currently amended) An apparatus according to claim 8, including an orienting device to adjust alignment of electronic components the packaged semiconductor devices and/or to locate the positions of defective components ones of the packaged semiconductor devices.

16. (Previously presented) An apparatus according to claim 15, wherein the orienting device is an image recognition vision system.

17. (Currently amended) An apparatus according to claim 9, wherein the inscribing device is a laser device which generates a laser beam operative to mark a surface of an electronic device the packaged semiconductor device by heating said the surface.

18. (Currently amended) An apparatus according to claim 17, wherein: the mounting means device comprises a film of transparent tape with an adhesive surface on which electronic components the packaged semiconductor devices are mountable; and the laser device is operative to direct the laser beam generated thereby through the film toward the adhesive surface thereof to mark electronic components packaged semiconductor devices mounted on said the adhesive surface.

19. (Currently amended) An apparatus according to claim 18, including an inverting device to invert the transparent tape to expose the surface of each electronic component that is packaged semiconductor device mounted on said adhesive surface of the transparent tape to the laser device for marking.

20-21. (Canceled)

22. (New) An apparatus according to claim 12, wherein the conveyor is an XYZ-Theta table.

23. (New) A method according to claim 1, wherein the packaged semiconductor devices are maintained in a substantially coplanar relationship on the mounting device during testing.

24. (New) A method according to claim 1, wherein the packaged semiconductor devices are tested in subsets selected such that adjacent devices are not tested simultaneously.

25. (New) An apparatus according to claim 8, wherein the packaged semiconductor devices are maintained in a substantially coplanar relationship on the mounting device during testing.

26. (New) An apparatus according to claim 8, wherein the packaged semiconductor devices are tested in subsets selected such that adjacent devices are not tested simultaneously.